# DAP<sup>™</sup>-AM Series - Metal Powders for 3D printing -

Daido Alloy Powder – for Additive Manufacturing

## Die steel-based powder for printing large products DAP<sup>™</sup>-AMLTX

DAP<sup>™</sup>-AM LTX have been developed by adjusting chemical composition of metal powder suitable for additive manufacturing for large products exceeding 150 mm square by SLM.

#### **Characteristics**

Powders produced by gas atomization and have low oxygen content and high flowability.

•Reduces internal strain during molding compared to H13 and DAP<sup>™</sup>-AM HTC, suitable for large-sized products.

•Thermal conductivity is equivalent to SKD61. Mold performance is expected to be similar.

·Cois not contained.

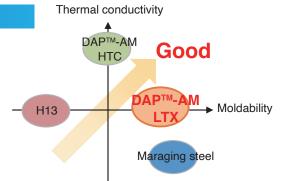


Fig.1 Characteristics of DAP™-AM LTX compared to other powders.

### Major applications

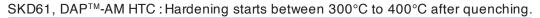
Pins and inserts etc. with cooling holes

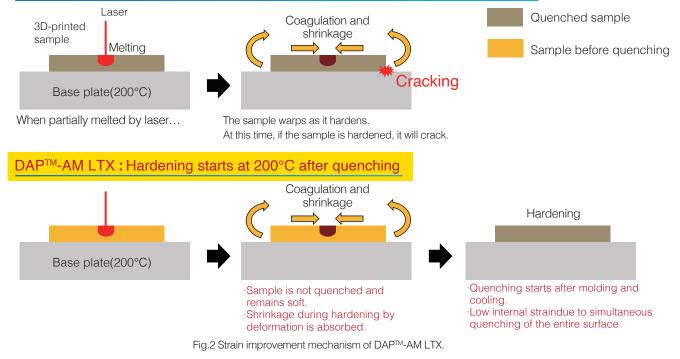
Typical chemical composition(mass%) Hardness range (HRC) Particle size(μm)   C Si Ni Cr Mo V (HRC) -53/+25	Туріс	al chen	nical co	mposit	Particle size			
								Particle size(µm)
$0.25$ 0.1 6 5.2 1.2 0.4 $40 \sim 54$ $-53/+25$	C	Si	Ni	Cr	Mo	V	(HRC)	
	0.25	0.1	6	5.2	1.2	0.4	40~54	-53/+25

#### Why does internal strain remain low?

By designing alloys with a martensitic transformation starting temperature (the temperature at which they become hardened by quenching) lower than the molding temperature, the material is not quenched during the molding process, and is soft and less prone to distortion accumulation.

After the molding process is completed, the entire molding part is simultaneously quenched and hardened.





#### Influence of base plate temperature on internal strain

Stable low strain can be obtained by heating the base plate to 160°C or higher. If heating to 160°C or higher is impossible, adjust the temperature around 50°C to reduce strain.

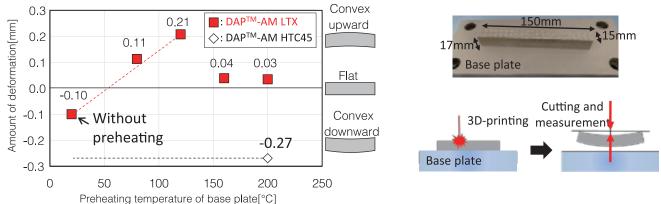


Fig.3 Relationship between preheating temperature of base plate and amount of 3D-printed sample.

#### **Properties**

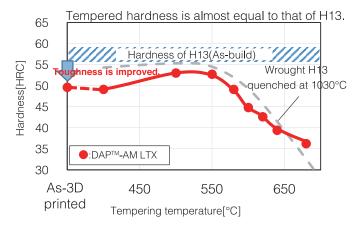


Fig.4 Tempering Hardness of DAP<sup>m</sup>-AM LTX compared to H13. (Tempering [T°C × 1h] 2 times, base plate temperature 120°C)



Fig.6 Mold manufacturing process of DAP<sup>™</sup>-AM LTX

Thermal conductivity is equivalent to H13. 35 Thermal conductivity[W/mk] 30 25 20 ● :DAP™ -AM LTX 15 :Wrought H13 :Wrought maraging steel 10 0 200 400 600 Temperature[°C]

Fig.5 Thermal conductivity of DAP<sup>™</sup>-AM LTX compared to H13 and maraging steel.

Large products exceeding 150 mm square can be modeled.

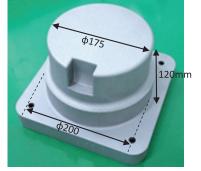


Fig.7 The example of 3D-printed sample of DAP<sup>™</sup>-AM LTX.



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